



Title of Change:	Final PCN for wafer fab transfer from Gifu in Japan to United Microelectronics Corp (UMC) in Taiwan (Group DH).			
Proposed first ship date:	14 January 2016			
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>			
Samples:	Contact your local ON Semiconductor Sales Office			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>.			
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.			
Change Part Identification:	Affected products will be identified with date code.			
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change		<input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change	
			<input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gifu, Japan		<input checked="" type="checkbox"/> External Foundry/Subcon site(s) UNITED MICROELECTRONICS CORP Taiwan	
Description and Purpose:				
This is a Final Process Change Notification to announce the transfer of products from ON Semiconductor wafer fabrication sites located in Gifu Japan to the wafer fabrication United Microelectronics Corp (UMC) in Taiwan. The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.				
Reliability Data Summary:				
Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated VDSS	1008 hrs	0/22
HTGB	JESD22-A108	Ta=150°C, 100% max rated VGSS	1008 hrs	0/22
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0/22
IOL	MIL-STD-750 (M1037) AEC-Q101	delta Tj=100°C	7500 cyc	0/22
TC	JESD22-A104	Ta= -55°C to +150°C	200 cyc	0/22
H ³ TRB	JESD22-A110	85°C, 85% RH, 80% max rated VDSS	1008 hrs	0/22
AC	JESD22-A118	121°C, 100% RH, 2.03×10 ⁵ Pa, unbiased	96 hrs	0/22
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/22
SD	JSTD002	Ta = 245C, 10 sec		0/22



Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ATP212-TL-H	ATP401-TL-H